Sync DRAM Code Information(1/2)

Last Updated : February 2009

K	4	S	X	X	X	X	X	X	X	-	X	X	X	X	X	X	X
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

1. Memory (K)

2. DRAM : 4

3. Small Classification
S : SDRAM

4~5. Density,Refresh
16 : 16M, 2K/32ms
28 : 128M, 4K/64ms
51 : 512M, 8K/64ms
56 : 256M, 8K/64ms
64 : 64M, 4K/64ms
1G : 1G, 8K/64ms

6~7. Organization
04 : x4
06 : x4 Stack
07 : x8 Stack
08 : x8
16 : x16
32 : x32

8. Bank
2 : 2 Bank
3 : 4 Bank

9. Interface, VDD, VDDQ
2 : LVTTL, 3.3V, 3.3V
L : LVCMOS, 2.5V, 2.5V

10. Generation

11. "—"

12. Package
N : STSOP2
T : TSOP2
U : TSOP2 (Lead-Free)
L : TSOP2 (Lead-Free & Halogen-Free)
V : STSOP2 (Lead-Free)

Note : In a special case, TSOP2 package code "-U" of SDR 256Mb J-die/128Mb K-die and sTSOP2 "V" of 256Mb J-die stand for Lead-free and Halogen free,

13. Temp, Power
C : Commercial, Normal (0℃ ~ 70℃)
L : Commercial, Low (0℃ ~ 70℃)
I : Industrial, Normal (-40℃ ~ 85℃)
P : Industrial, Low (-40℃ ~ 85℃)
E : Extended, Normal (-25℃ ~ 85℃)
N : Extended, Low (-25℃ ~ 85℃)

14~15. Speed (Wafer / Chip Biz / BGD : 00)
50 : 5ns
55 : 5.5ns
60 : 6ns
70 : 7ns
75 : 7.5ns, PC133
80 : 8ns

Sync DRAM Code Information(2/2)

Last Updated : February 2009

K	4	S	X	X	X	X	X	X	X	-	X	X	X	X	X	X	X
1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18

16. Packing "Packing Type Reference"

- Common to all products, except of Mask ROM
- Divided into TAPE & REEL(In Mask ROM, divided into TRAY, AMMO Packing Separately)

Divide	Packing Type	New Marking
Component	TAPE & REEL	T
	Other (Tray, Tube, Jar)	0 (Number)
	Stack	S
Module	MODULE TAPE & REEL	P
	MODULE Other Packing	M

17~18. Customer "Customer List Reference"